

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of	:	Customer Number: 89518
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Mou-Shiung Lin, et al.	:	Confirmation Number: 8665
	:	
Application No.: 10/755,042	:	Group Art Unit: 2815
	:	
Filed: January 09, 2004	:	Examiner: JEROME JACKSON, JR.
	:	
For: INTEGRATED CHIP PACKAGE STRUCTURE USING SILICON SUBSTRATE AND METHOD OF MANUFACTURING THE SAME		

INFORMATION DISCLOSURE STATEMENT

Mail Stop RCE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF ELECTRONIC TRANSMISSION

I hereby certify that this correspondence is being electronically-transmitted to the United States Patent and Trademark Office on **June 27, 2011**.

/s/lynne j. craig /
Lynne J. Craig

Dear Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

The references herein were cited in a Taiwan opposition proceeding of corresponding Taiwan Case No. 090131210N01.

This Information Disclosure Statement is being filed with a Request for Continued Examination AND before the mailing date of a first Office Action on the merits. No certification or fee is required.

10/755,042

Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account 502624 and please credit any excess fees to such deposit account.

Respectfully submitted,

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